# **Schottky Barrier Diode**

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

#### **Features**

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage 0.28 V (Typ) @ I<sub>F</sub> = 1.0 mAdc
- Low Reverse Current
- Lead–Free Plating
- Pb-Free Package is Available



# ON Semiconductor®

http://onsemi.com

# **40 V SCHOTTKY BARRIER DIODE**





**CASE 502 PLASTIC** 

## **MARKING DIAGRAM**



= Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit	
Peak Reverse Voltage	$V_{RM}$	40	V	
Reverse Voltage	V <sub>R</sub>	30	V	
Forward Continuous Current (DC)	I <sub>F</sub>	30	mA	
Peak Forward Surge Current	I <sub>FSM</sub> 500			
ESD Rating: Class 1C per Human Body Model Class A per Machine Model				

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

1. FR-5 Minimum Pad.

# ORDERING INFORMATION

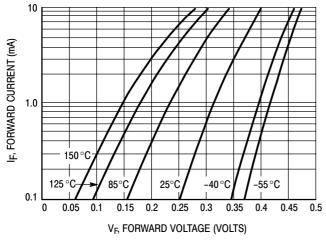
Device	Package	Shipping <sup>†</sup>
RB751S40T1	SOD-523	4000/Tape & Reel
RB751S40T1G	SOD-523 (Pb-Free)	4000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \mu A)$	V <sub>(BR)R</sub>	30	-	-	V
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	Ст	-	2.0	2.5	pF
Reverse Leakage (V <sub>R</sub> = 30 V)	I <sub>R</sub>	_	300	500	nAdc
Forward Voltage (I <sub>F</sub> = 1.0 mAdc)	V <sub>F</sub>	-	0.28	0.37	Vdc



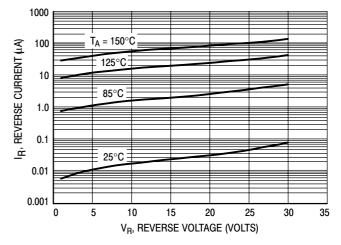


Figure 1. Typical Forward Voltage

Figure 2. Reverse Current versus Reverse Voltage

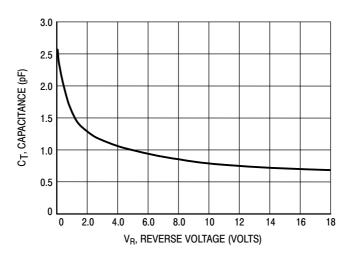
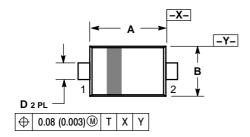
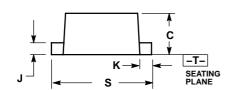


Figure 3. Typical Capacitance

# **PACKAGE DIMENSIONS**

SOD-523 CASE 502-01 ISSUE B

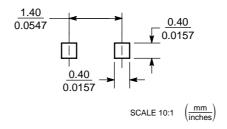




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.10	1.20	1.30	0.043	0.047	0.051	
В	0.70	0.80	0.90	0.028	0.032	0.035	
С	0.50	0.60	0.70	0.020	0.024	0.028	
D	0.25	0.30	0.35	0.010	0.012	0.014	
J	0.07	0.14	0.20	0.0028	0.0055	0.0079	
K	0.15	0.20	0.25	0.006	0.008	0.010	
S	1.50	1.60	1.70	0.059	0.063	0.067	

#### **SOLDERING FOOTPRINT\***



<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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